

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	"10806644".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:05
S2	3	"806644".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:07
S3	14	"goudarzi, vahid".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:09
S4	4	((("5411199") or ("5167361"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 15:23
S5	95	"motorola".as. and shield and substrate and "method".ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:26
S6	5	"motorola".as. and shield.ti. and substrate and "method".ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:32
S7	1	"conductive shield track"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:33
S8	132	"shield track"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 14:28

S9	132	solder and ("over printing" or overprinting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:54
S10	38	solder with ("over printing" or overprinting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:54
S11	2	("5411199").URPN.	USPAT	OR	ON	2005/05/04 16:22
S12	1	shield with (solder adj clad\$4)	USPAT	OR	ON	2005/05/05 09:21
S13	534	(257/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 09:40
S14	1227	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 10:05
S15	359	(257/710).CCLS.	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 13:47
S16	4437	solder and flux and dip\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:49
S17	1470	solder and (flux with dip\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:49
S18	1003	solder with (flux with dip\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:50

S19	842	solder with (flux with (dipped or dipping))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:50
S20	497	solder with (flux with dipped)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:50
S21	52	(US-20010030882-\$ or US-20030057575-\$ or US-20030073266-\$ or US-20030178709-\$ or US-20030183920-\$ or US-20030193082-\$ or US-20030205797-\$ or US-20040007385-\$ or US-20040012931-\$ or US-20040046245-\$ or US-20040080044-\$ or US-20040178494-\$ or US-20040259434-\$).did. or (US-5153709-\$ or US-5166773-\$ or US-5167361-\$ or US-5168344-\$ or US-5223741-\$ or US-5346118-\$ or US-5411199-\$ or US-5498900-\$ or US-5572070-\$ or US-5620927-\$ or US-5641713-\$ or US-5706579-\$ or US-5821161-\$ or US-5883425-\$ or US-5919329-\$ or US-5936846-\$ or US-5945735-\$ or US-5956576-\$ or US-5970319-\$ or US-6008536-\$ or US-6015722-\$ or US-6115262-\$ or US-6169253-\$ or US-6255730-\$ or US-6262479-\$ or US-6274214-\$). did. or (US-6303872-\$ or US-6310900-\$ or US-6405920-\$ or US-6459160-\$ or US-6476332-\$ or US-6489558-\$ or US-6636538-\$ or US-6696645-\$ or US-6736308-\$ or US-6747350-\$ or US-6781231-\$ or US-6784535-\$ or US-6882041-\$). did.	US-PGPUB; USPAT	OR	ON	2005/11/17 13:24
S22	2	"shield track" and (cladding or cladded)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 15:18

S23	4915	(emi or rfi) with (seal or shield)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 15:18
S24	162	(emi or rfi) with (seal or shield) and clad\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 15:19
S25	8	("3649803" "4339628" "5357404" "5358774" "5371404").PN. OR ("5411199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/17 15:27